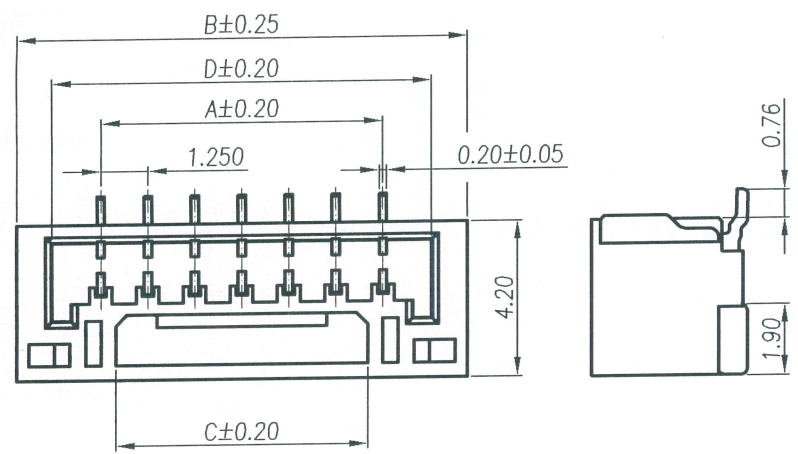


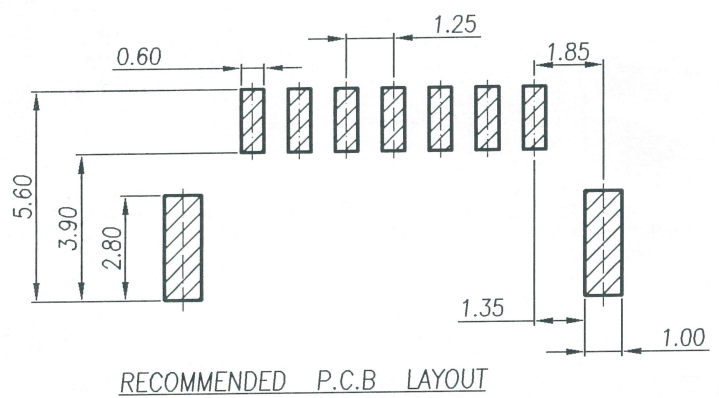
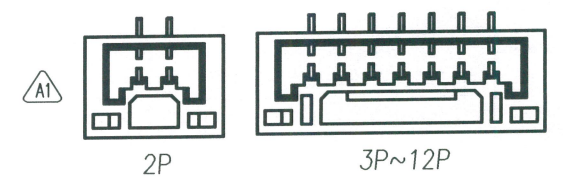
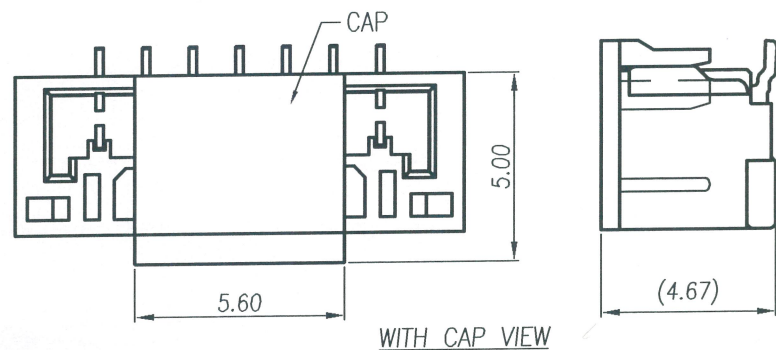
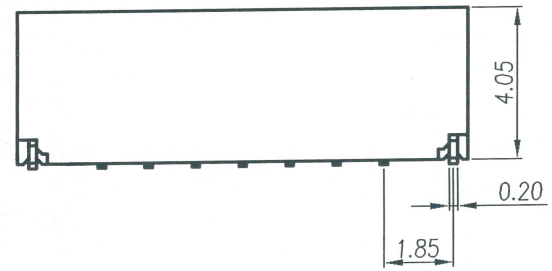
**RoHS Compliant**



REV	MODIFICATION	DATE	DRAW	REQUIRE
A0	Refer to MA20170501	20170531	Abel	Abel
A1	Refer to ECN20191101	20191122	Anita	Abel



PIN	DIMENSIONS			
	A	B	C	D
02	1.25	5.75	2.20	3.75
03	2.50	7.00	3.30	5.00
04	3.75	8.25	4.55	6.25
05	5.00	9.50	4.55	7.50
06	6.25	10.75	6.55	8.75
07	7.50	12.00	6.55	10.00
08	8.75	13.25	6.55	11.25
09	10.00	14.50	6.55	12.50
10	11.25	15.75	8.55	13.75
11	12.50	17.00	8.55	15.00
12	13.75	18.25	8.55	16.25

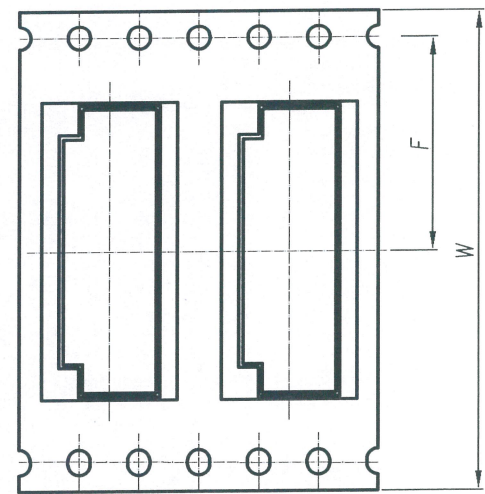
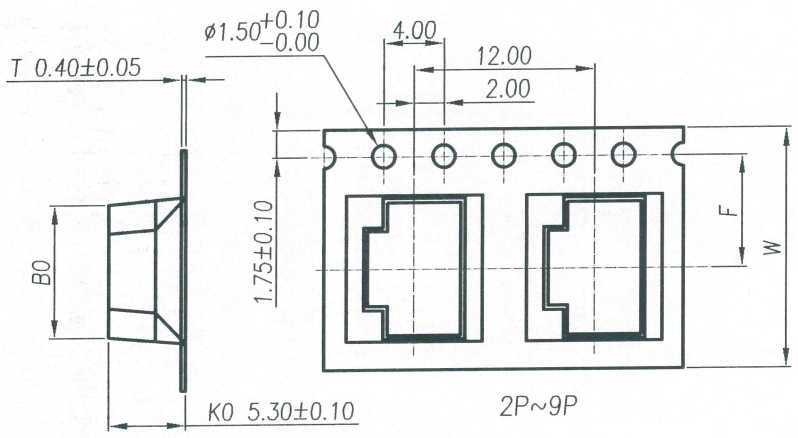
**Specification**  
 1.Current Rating:1A AC/DC  
 2.Voltage Rating:50V AC/DC  
 3.Contact Resistance:30mΩ Max.  
 4.Insulation Resistance:100MΩ Min.  
 5.Withstand Voltage:AC500V/Minute  
 6.Operating Temperature:-25°C~+85°C  
**Material:**  
 1.Housing:Thermoplastic UL94V-0  
 2.Contact Pin:Copper Alloy T=0.20mm  
 3.Tab:Copper Alloy T=0.20mm  
**Finish:**  
 1.Housing:Natural  
 2.Contact Pin:Tin Plated  
 3.Tab:Tin Plated  
 Part No.:AS09700 XX 5 B 0 V  
 No. Of Pin ——— 5 ——— Packing  
 02~12 ——— 0:T&R With Cap  
 Housing Material ——— Plating  
 5:PA6T UL94V-0 Natural B:Matte Tin Plated



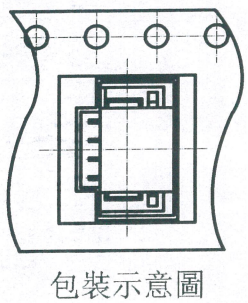
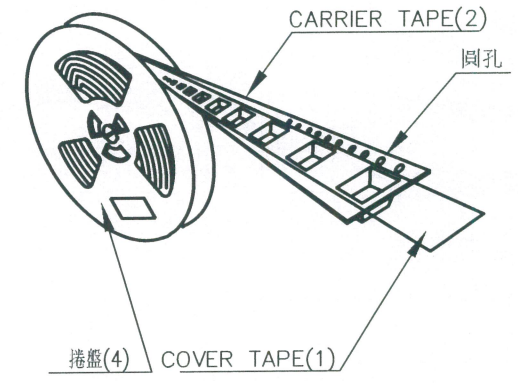
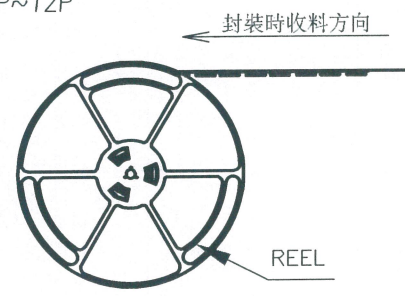
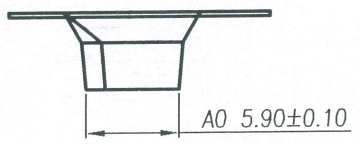
Confirmation signature			<b>金上達科技股份有限公司</b> GOLDENSUNDA TECHNOLOGY CO.,LTD			
	TOLERANCE UNLESS OTHERWISE SPECIFIED		PROV. 	TITLE: Wire To Board Wafer 1.25mm 180D SMT Single Row		
	.x± 0.35	x:± 2'	APR. <i>Yami</i>	PART NO. AS09700XX5B0V	DWG NO. AS09700XX5B0V	
	.xx± 0.25	.x:± 1'	CHK. <i>Abel</i>	UNITS: mm	<b>CUSTOMER DRAWING</b>	
.xxx± 0.15	.xx:± 0.5'	DRA. Anita 20191122	SIZE: <b>A4</b>	SCALE: FREE	SHEET 1 / 2	REV: A1

RoHS Compliant

REV	MODIFICATION	DATE	DRAW	REQUIRE
A0	Refer to MA20170501	20170531	Abel	Abel
A1	Refer to ECN20191101-5191104 Elen	20191122	Anita	Abel



- NOTES:
- ALL DIMENSIONS MEET EIA-481-D REQUIREMENTS.
  - MATERIAL: WHITE PS
  - CARRIER CAMER NOT TO EXCEED 1mm IN 250mm.
  - A0 AND B0 MEASURED ON A PLANE 0.3mm ABOVE THE BOTTOM OF THE POCKET.
  - K0 MEASURED FROM A PLANE ON THE INSIDE BOTTOM OF THE POCKET TO THE TOP SURFACE OF THE CARRIER.
  - Q'ty/Reel:1000PCS. (LENGTH:12.5m) 130 模
  - THICKNESS:0.4±0.05mm.
  - REEL:13" 膠盤



CTK.	DIMENSIONS			Q'ty/BOX
	W	F	B0	
2P	16.0	7.500	6.100	19*1000
3P	16.0	7.500	7.350	19*1000
4P	16.0	7.500	8.600	19*1000
5P	24.0	11.500	9.850	14*1000
6P	24.0	11.500	11.100	14*1000
7P	24.0	11.500	12.350	14*1000
8P	24.0	11.500	13.600	14*1000
9P	24.0	11.500	14.850	14*1000
10P	32.0	14.200	16.100	11*1000
12P	32.0	14.200	18.600	11*1000

Confirmation signature



金上達科技股份有限公司  
GOLDENSUNDA TECHNOLOGY CO.,LTD

TOLERANCE UNLESS OTHERWISE SPECIFIED		PROJ.	TITLE: Wire To Board Wafer 1.25mm 180D SMT Single Row	
.x± 0.35	x.*± 2'	APR. <i>Yami</i>	PART NO. AS09700XX5B0V	DWG NO. AS09700XX5B0V
.xx± 0.25	.x.*± 1'	CHK. <i>Abel 1/5/22</i>	UNITS: mm	CUSTOMER DRAWING
.xxx± 0.15	.xx.*± 0.5'	DRA. Anita 20191122	SIZE: <b>A4</b>	SCALE FREE SHEET 2 / 2 REV A1 V